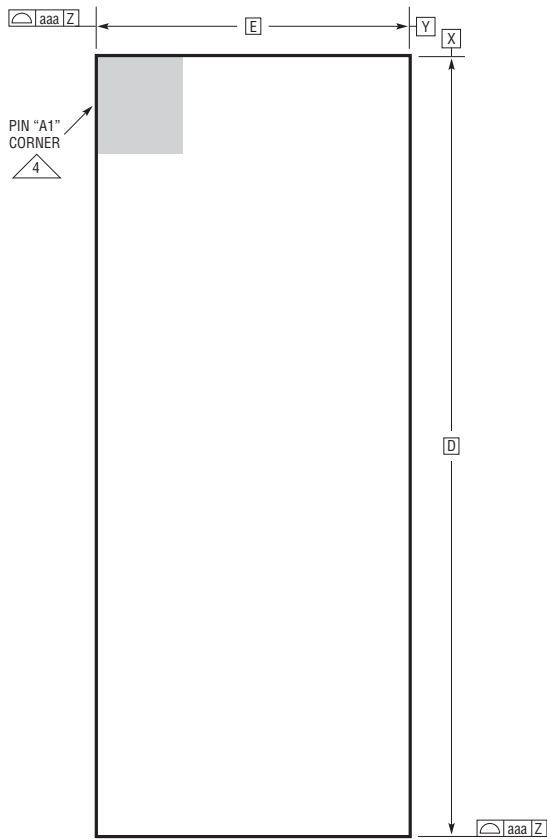
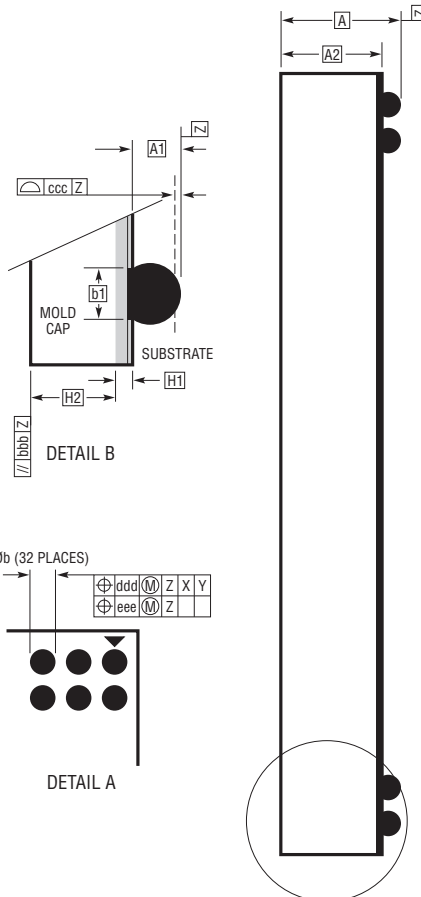


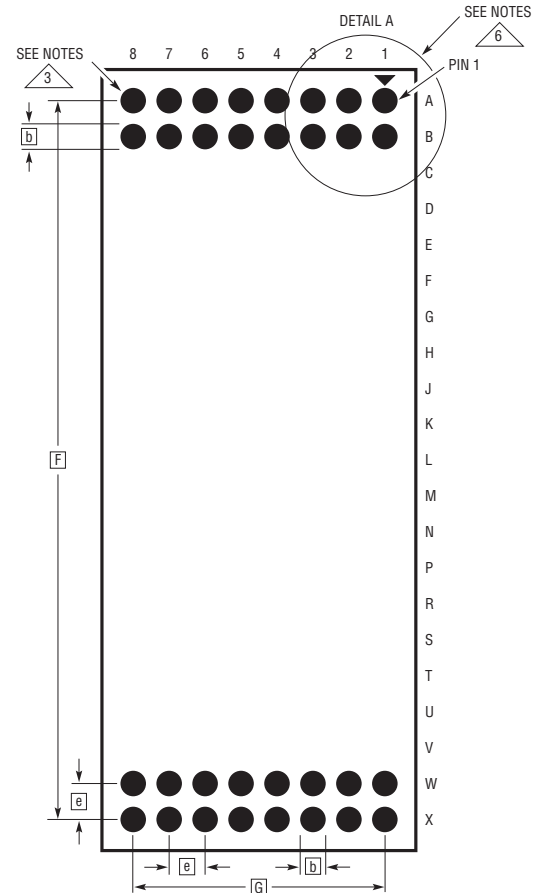
**BGA Package**  
**32-Lead (22mm × 9mm × 3.06mm)**  
 (Reference LTC DWG# 05-08-1975 Rev A)



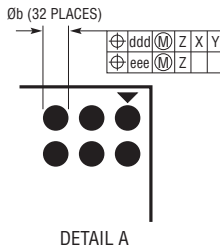
PACKAGE TOP VIEW



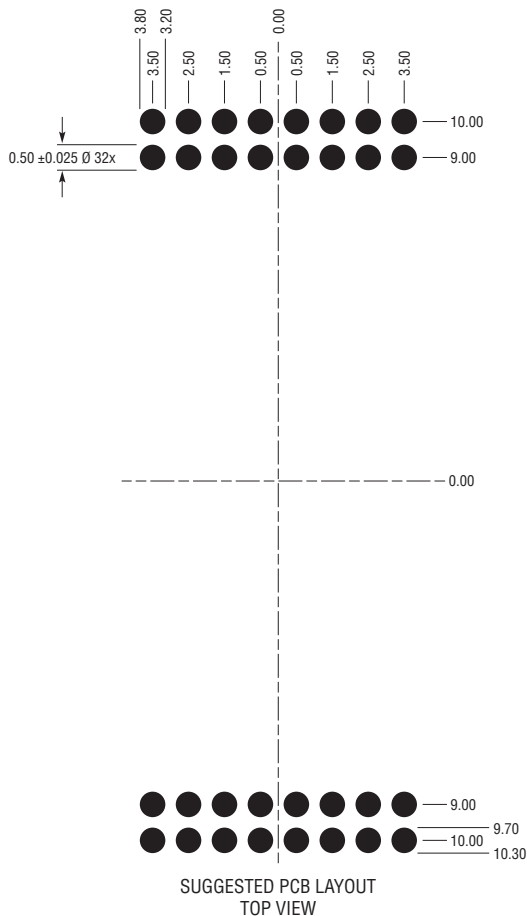
DETAIL B  
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



DETAIL A



SUGGESTED PCB LAYOUT  
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.81	3.06	3.31	
A1	0.40	0.50	0.60	BALL HT
A2	2.41	2.56	2.71	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		22.0		
E		9.0		
e		1.0		
F		20.0		
G		7.0		
H1	0.46	0.56	0.66	SUBSTRATE THK
H2	1.95	2.00	2.05	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 32

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

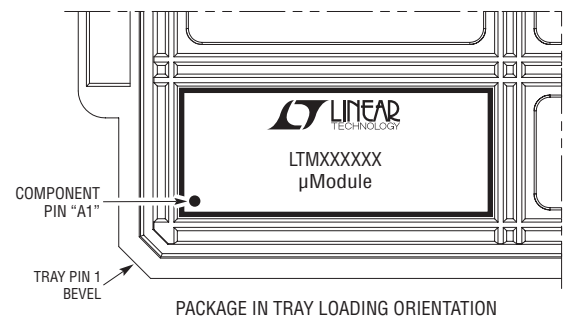
2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION